

## Package Material Composition and Mass Calculation

Customer: PLX TECHNOLOGY INC.  
 Package: PBGA 272L  
 Device Type: PCI9656-BA66BI G  
 Body Size: 27 X 27  
 Die Size: 176 X 171

Date: 28/2/2005

	name	composition	%	mg.(ave)	mg.	%	PPM
Mold Compound	KE-G1250				<u>1322.1</u>	<u>57.66</u>	<u>576,556</u>
		Silica Fused	60676-86-0	84 ~ 92	1163.45	50.74	507,369
		Epoxy Resin		5 ~ 9	79.33	3.46	34,593
		Phenolic Resin		4 ~ 8	66.11	2.88	28,828
		Other		<1	13.22		
Die Attach	AB 2000B				<u>1.7</u>	<u>0.07</u>	<u>741</u>
		Silver	7440-22-4	70~90	1.19	0.05	519
		Epoxy Resin		1~10	0.085	0.00	37
		Diester		5~20	0.17	0.01	74
		Polymeric Resin		1~10	0.085		
		Ester		5~20	0.17		
Substrate					<u>565.2</u>	<u>24.65</u>	<u>246,479</u>
		Copper	7440-50-8	30	169.56	7.39	73,944
		PSR-4000 AUS 5	64742-94-5	4.3	24.30	1.06	10,599
		Nickel	7440-02-0	4.2	23.74	1.04	10,352
		Gold	7440-57-5	0.5	2.83	0.12	1,232
		BT	75-21-8	57.4	324.42		
		Epoxy Resin	78-85-1	3.6	20.35		
Die	Silicon	Silicon			<u>26</u>	<u>1.13</u>	<u>11,338</u>
Wire	TANAKA GMH				<u>10.9</u>	<u>0.48</u>	<u>4,753</u>
		Au		99.99	10.8989	0.48	4,753
		Ion Impurities		0.01	0.0011	0.00	0.475
Solder Ball	Sn/Ag/Cu				<u>367.2</u>	16.01	160132.57
		Sn		96.5	354.35	15.45	154527.93
		Ag		3	11.02	0.48	4803.98
		Cu		0.5	1.84	0.08	800.66
Total					<u>2293.1</u>	100.00	1,000,000